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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/784,436	02/23/2004	William M. Hiatt	2269-5868US (01-0764.00/U	2546
24247 TRASK BRITT	7590 02/26/2007 Γ	EXAMINER		
P.O. BOX 2550			SCHILLINGER, LAURA M	
SALT LAKE CITY, UT 84110			ART UNIT	PAPER NUMBER
			2813	
SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MONTHS		02/26/2007	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

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+k	,	Application No.	Applicant(s)		
Office Action Summary		10/784,436	HIATT, WILLIAM M.		
		Examiner	Art Unit		
		Laura M. Schillinger	2813		
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the c	orrespondence address		
WHIC - Exte after - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DANSIONS of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. O period for reply is specified above, the maximum statutory period we are to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tin will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	N. nety filed the mailing date of this communication. D. (35 U.S.C. \$ 133)		
Status		•			
1)⊠	Responsive to communication(s) filed on 29 Ja	anuary 2007.			
	☐ This action is FINAL . 2b) ☑ This action is non-final.				
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is				
	closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.		
Dispositi	ion of Claims				
5)□ 6)⊠ 7)□	Claim(s) <u>1-9</u> is/are pending in the application. 4a) Of the above claim(s) is/are withdraw Claim(s) is/are allowed. Claim(s) <u>1-9</u> is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or				
Applicati	ion Papers				
10)	The specification is objected to by the Examiner The drawing(s) filed on is/are: a) acce Applicant may not request that any objection to the o Replacement drawing sheet(s) including the correcti The oath or declaration is objected to by the Examiner	epted or b) objected to by the I drawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).		
Priority ι	ınder 35 U.S.C. § 119				
12) <u>□</u> a)[Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prioric application from the International Bureau See the attached detailed Office action for a list of	s have been received. s have been received in Application ity documents have been received (PCT Rule 17.2(a)).	on No ed in this National Stage		
2)	t(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO/SB/08) r No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ite		

Application/Control Number: 10/784,436

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DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-5,7, 9 are rejected under 35 U.S.C. 102(b) as being anticipated by Anthony (*836).

Anthony teaches the following claimed limitations as cited below:

1. (Original) A method for electrically coupling a first side of a semiconductor substrate to a second side of said semiconductor substrate, comprising:

forming a hole having an inner surface from a first side of a semiconductor substrate to a second side of said semiconductor substrate (Fig.1 (12)) and

plating said inner surface of said semiconductor substrate to form a plated conductive element by forcing a plating solution from said first side of said semiconductor substrate and exiting the plating solution to said second side of said semiconductor substrate through said hole (Fig.3 (18) and Col.5, lines: 45-50- teaching to cause the plating solution to flow through the holes).

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2. (Original) The method of claim 1, wherein forming said hole comprises at least one of ablating, mechanically drilling and chemically etching a portion of said semiconductor substrate from said first side to said second side (Col.2, lines: 45-55).

- 3. (Original) The method of claim 1, further comprising loading said semiconductor substrate into a plating fixture, said semiconductor substrate and said plating fixture cooperatively directing flow of a plating material through said hole of said semiconductor substrate (Co1.5, lines: 45-55).
- 4. (Original) The method of claim 1, wherein said plating comprises electroplating said inner surface of said semiconductor substrate defined by said hole (Fig.3 (18)).
- 5. (Original) The method of claim 1, wherein said plating process comprises electroless plating said inner surface of said semiconductor substrate defined by said hole (Col.1, lines: 55-62).
- 7. (Original) The method of claim 1, further comprising etching one of said first and second sides of said substrate to expose at least one end portion of said plated conductive element (inherent- laser drilling is an etching which ultimately exposes the end portion of the plated conductive element hole).
- 9. The method of claim 1, wherein said hole is between approximately 50 microns and 700 microns in diameter (Col. 2, lines: 1-5- 1mil =25.4 um).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 6 and 8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Anthony ('836) as applied to the claims above, and further in view of Bhatt et al ('218). Anthony teaches the conventional method of plating a through hole. However fails to explicitly teach that the technique of plating a filled through hole.

Bhatt et al teaches that both holes to be filled and unfilled need electroplating and further teaches to utilize capping layers:

- 6. The method of claim 1, further comprising forming a conductive cap on at least one end of said plated conductive element (Col.3, lines: 20-25)).
- 8. (Original) The method of claim 7, further comprising forming a conductive cap over said at least one end portion of said plated conductive element (Fig.1 (13)).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to utilize a conductive cap as taught by Bhatt in order to facilitate a connection with a filled hole as taught by Bhatt (Col.3, lines: 15-25)

Response to Arguments

Applicant's arguments with respect to the above claims have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Laura M. Schillinger whose telephone number is (571) 272-1697. The examiner can normally be reached on M-T, R-F 7:00-5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl W. Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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02/14/07

Laura M Schillinger Primary Examiner Art Unit 2813